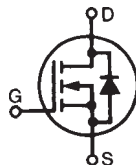


High Voltage HiperFET IXFP05N100M

(Electrically Isolated Tab)

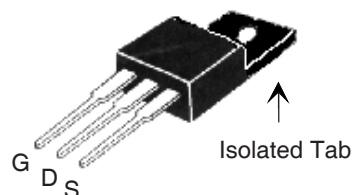
N-Channel Enhancement Mode
Avalanche Rated



$$\begin{aligned} V_{DSS} &= 1000V \\ I_{D25} &= 700mA \\ R_{DS(on)} &\leq 17\Omega \\ t_{rr} &\leq 300ns \end{aligned}$$

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	1000	V
V_{DGR}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}, R_{GS} = 1\text{ M}\Omega$	1000	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	$T_C = 25^\circ\text{C}$	700	mA
I_{DM}	$T_C = 25^\circ\text{C}$, pulse width limited by T_{JM}	3	A
I_A	$T_C = 25^\circ\text{C}$	1	A
E_{AS}	$T_C = 25^\circ\text{C}$	100	mJ
dv/dt	$I_S \leq I_{DM}, V_{DD} \leq V_{DSS}, T_J = 150^\circ\text{C}$	5	V/ns
P_D	$T_C = 25^\circ\text{C}$	25	W
T_J		- 55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		- 55 ... +150	$^\circ\text{C}$
T_L	1.6 mm (0.062 in.) from case for 10 s	300	$^\circ\text{C}$
T_{SOLD}	Plastic body for 10 s	260	$^\circ\text{C}$
M_d	Mounting torque	1.13/10	Nm/lb.in.
Weight		2.5	g

OVERMOLDED TO-220
(IXFP...M) OUTLINE



G = Gate D = Drain
S = Source

Features

- Plastic overmolded tab for electrical isolation
- International standard package
- Avalanche rated
- Low package inductance

Advantages

- Easy to mount
- Space savings
- High power density

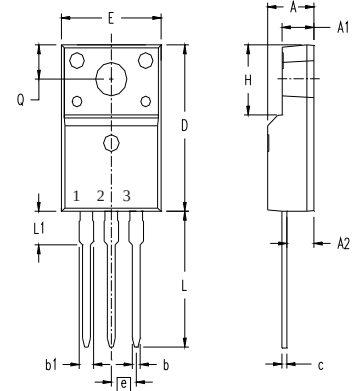
Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu\text{A}$	1000		V
$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5		4.5 V
I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100\text{ nA}$
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$ $T_J = 125^\circ\text{C}$			25 μA 500 μA
$R_{DS(on)}$	$V_{GS} = 10V, I_D = 375\text{mA}$, Note 1		15	17 Ω

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 20\text{V}$, $I_D = 500\text{mA}$, Note 1	0.55	0.93	S
C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$		260	pF
C_{oss}			22	pF
C_{rss}			8	pF
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 1\text{A}$ $R_G = 47\Omega$ (External)		11	ns
t_r			19	ns
$t_{d(off)}$			40	ns
t_f			28	ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 1\text{A}$		7.8	nC
Q_{gs}			1.4	nC
Q_{gd}			4.1	nC
R_{thJC}				5.0 $^\circ\text{C/W}$

Source-Drain Diode

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$ unless otherwise specified)		
		Min.	Typ.	Max.
I_S	$V_{GS} = 0\text{V}$			750 mA
I_{SM}	Repetitive, pulse width limited by T_{JM}			3 A
V_{SD}	$I_F = I_S$, $V_{GS} = 0\text{V}$, Note 1			1.5 V
t_{rr}	$I_F = 1\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$, $V_R = 100\text{V}$, $V_{GS} = 0\text{V}$		1.8	ns
I_{RM}				A
Q_{RM}			200	nC

ISOLATED TO-220 (IXFP...M)



Terminals: 1 - Gate
2 - Drain (Collector)
3 - Source (Emitter)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.177	.193	4.50	4.90
A1	.092	.108	2.34	2.74
A2	.101	.117	2.56	2.96
b	.028	.035	0.70	0.90
b1	.050	.058	1.27	1.47
c	.018	.024	0.45	0.60
D	.617	.633	15.67	16.07
E	.392	.408	9.96	10.36
e	.100 BSC		2.54 BSC	
H	.255	.271	6.48	6.88
L	.499	.523	12.68	13.28
L1	.119	.135	3.03	3.43
ØP	.121	.129	3.08	3.28
Q	.126	.134	3.20	3.40

Notes:1. Pulse test, $t \leq 300 \mu\text{s}$; duty cycle, $d \leq 2\%$.

PRELIMINARY TECHNICAL INFORMATION

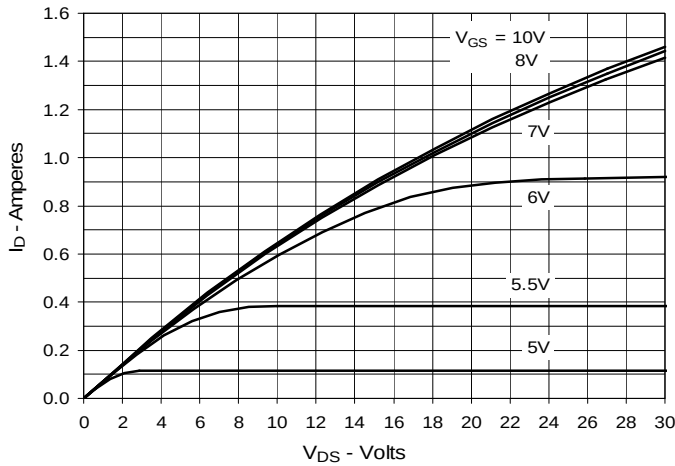
The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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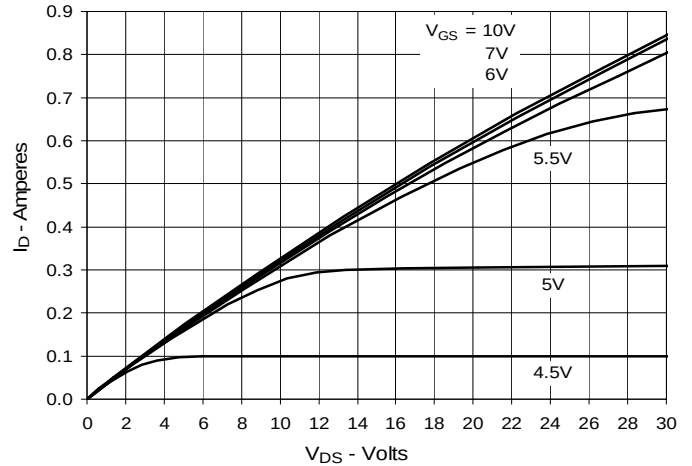
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338 B2
4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

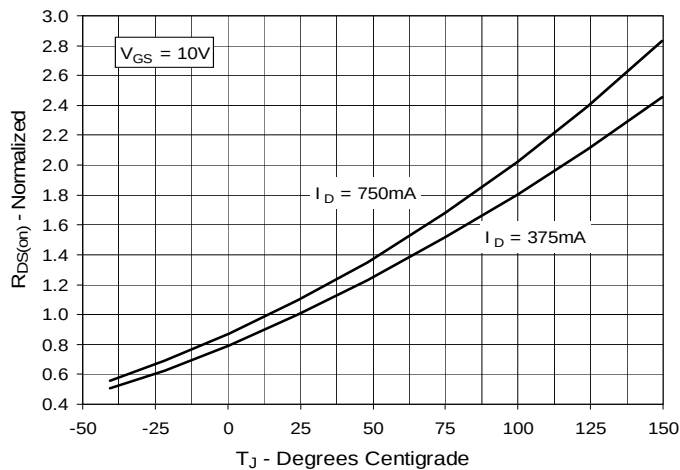
**Fig. 1. Output Characteristics
@ 25°C**



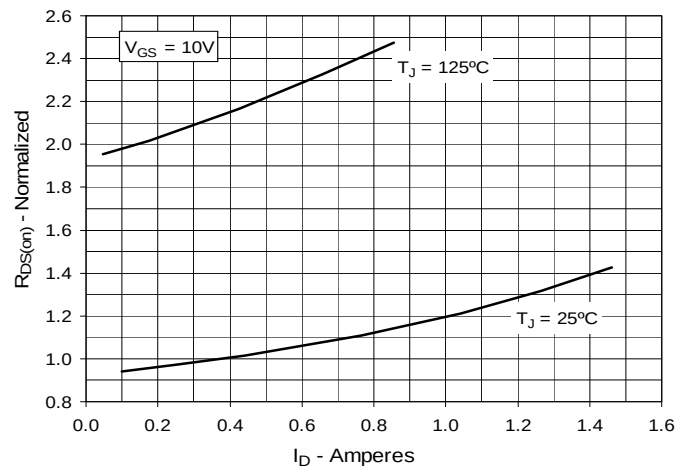
**Fig. 2. Output Characteristics
@ 125°C**



**Fig. 3. $R_{DS(on)}$ Normalized to $I_D = 375\text{mA}$
Value vs. Junction Temperature**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 375\text{mA}$
Value vs. Drain Current**



**Fig. 5. Maximum Drain Current vs.
Case Temperature**

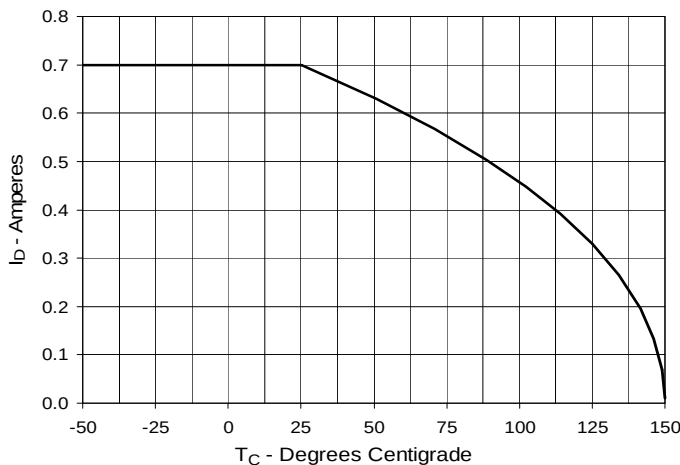


Fig. 6. Input Admittance

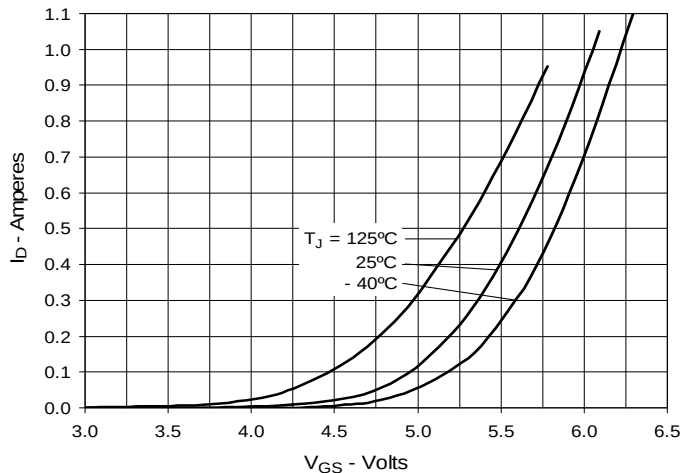
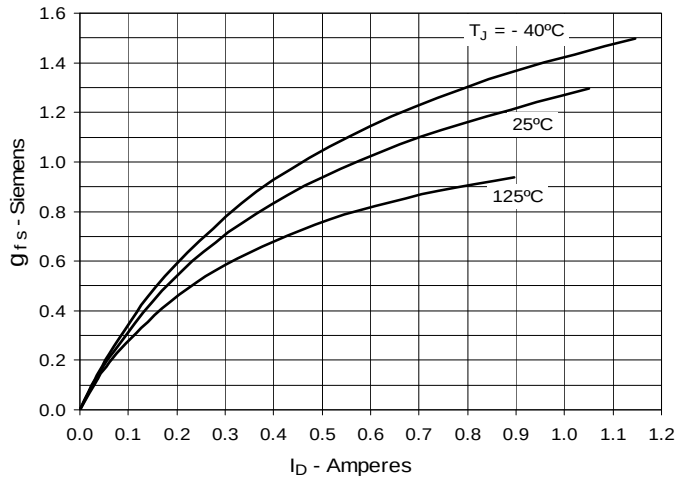
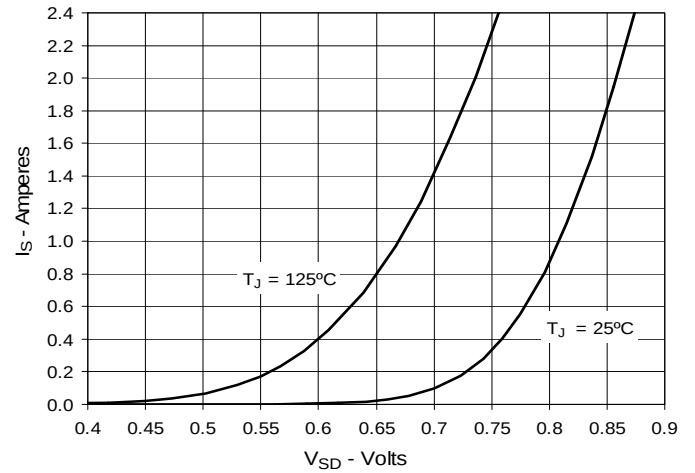
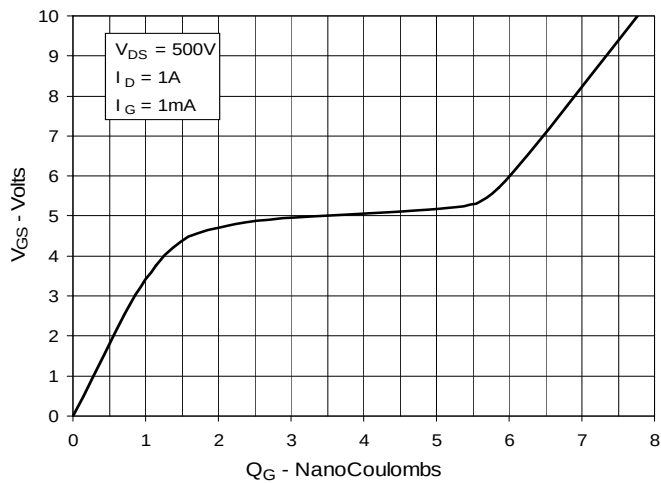
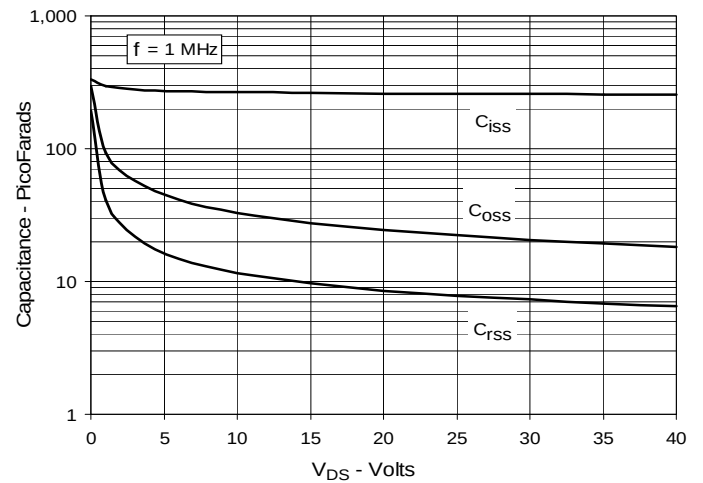


Fig. 7. Transconductance

Fig. 8. Forward Voltage Drop of Intrinsic Diode

Fig. 9. Gate Charge

Fig. 10. Capacitance

Fig. 11. Maximum Transient Thermal Impedance
